Global Headquarters

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Press Release

Kester to Participate in Numerous Activities During APEX 2007

ITASCA, IL — February 9, 2007 — Kester will provide lead-free soldering products, lead-free resources and technologies in booth 1542 at the upcoming APEX 2007 exhibition and conference, scheduled to take place February 20 to 22, 2006, in Los Angeles.

Kester will present its latest lead-free soldering products and award winning K100LD solder for lead-free wave, selective and hand-soldering applications.

Kester will also have Q&A sessions at its booth to answer any issue with lead-free assembly. Peter Biocca and Brian Smith will be available to assemblers who have questions, and each attendee will be given the latest Kester Lead-free Solutions CD.

Additionally, Peter Biocca will present a paper called "Case Study on the Validation of SAC305 and SnCu-based solders in SMT, Wave and Hand-soldering at the Contract Assembler Level." This is a joint paper between Kester and SMT Dynamics showing the implementation of large-volume assembly with lead-free, and will focus on defect-free, lead-free assembly with K100 solder and SAC305.

On Tuesday, February 20, Greg Munie, Ph.D., will present during the IPC International Technology Roadmap for 2006/2007, which will take place from 3:15-4:45 p.m. Presentations will highlight the various concepts used for developing the new roadmap and how it mirrors other roadmaps for the semiconductor industry and the OEM customer.

Peter also will chair the Test and Inspection session on Wednesday 21, 2007, from10:15-11:15 a.m.

On Wednesday, February 21 from 1:30 – 3:30 p.m., Kester will participate in the Rework, Repair and Reliability session of the technical conference. Rework and repair are difficult tasks that need to be performed well to ensure good product quality. This session focuses on repair and rework in the era of lead-free. The presentations will bring the latest information on developments in repair technology. Brian will present "Determining the Reliability of Tacky Fluxes in Varying Soldering Applications" and Peter will present "Lead-free Rework Practical Experiences with SAC and SnCu Alloys."

As an additional benefit for visitors, Kester will assist Bob Willis in his Q&A in reference to lead-free assembly. Bob will have a Process Advice & Defect Clinic on the show floor that is sponsored by *Global SMT & Packaging* Magazine and the IPC. Kester experts will help Bob respond to visitor questions that relate to lead-free assembly. Bob operates Electronic Presentation Services, a training and consultancy business based in England, and is technical director of the SMART Group. He is a specialist in implementing SMT and has been involved in the introduction and implementation of lead-free process technology for the last five years.

As always, Kester's global lead-free team of technical engineers will be present to answer all lead-free questions that companies may have about lead-free assembly. Be sure to stop by booth 1542 for more information.

For more information on Kester’s participation at APEX 2007, or Kester’s full line of products and services including SE-CURE™ and InnovaBond™ products, contact Kester by phone at (+1) 847-297-1600 or 800-2-KESTER (53-7837), by fax at (+1) 847- 699-5548, or by e-mail at customerservice@kester.com. Kester’s Web site may be found at www.kester.com.

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Founded in 1899, Kester is a world-renowned supplier of solder and related materials and services to the electronics assembly, micro-component, industrial soldering, hardware/retail and wholesale plumbing markets. Kester is known for high quality, advanced technology and superior technical support. With headquarters in Des Plaines, IL, Kester has additional manufacturing facilities in the United States, Mexico, Canada, Singapore, Germany, Japan, Brazil, Taiwan, Malaysia and China. Its worldwide manufacturing and technical capabilities provide the support required to serve major electronics manufacturing services providers and OEMs.